Product End-of-Life Disassembly Instructions

<table>
<thead>
<tr>
<th>Marketing Name / Model [List multiple models if applicable.]</th>
<th>Product Category</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP Omni PC</td>
<td>Integrated PC</td>
</tr>
</tbody>
</table>

**Purpose**: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

### 1.0 Items Requiring Selective Treatment

1. Items listed below are classified as requiring selective treatment.
2. Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>10</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB / PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

1. Place the system
2. Disassemble hinge cover & access door
3. Disassemble stand
4. Remove ODD&TOP Perf
5. Disassemble rear cover
6. Disassemble HDD
7. Disassemble CPU&I/O Shielding
8. Disassemble speaker
9. Disassemble stand support
10. Disassemble CPU H/S
11. Disassemble FAN
12. Unplug cable
13. Disassemble WLAN
14. Disassemble INVERTER
15. Disassemble MB
16. Remove power switch card
17. Disassemble webcam & antenna cable
18. Separate BASE pan & bezel

### 3.2 Optional Graphic

If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Do cosmetic check then place unit on work table.

19. Disassemble hinge cover & access door

- Disassemble hinge cover & R/L access door.

20. Disassemble stand

Remove 3 screws for fixing stand.
Place stand to specified area.

21. Remove ODD & TOP Perf

- Remove 2 screws for fixing top perf.
- Take top perf.

- Remove one screw for fixing ODD, Put ODD to specified area.

22. Disassemble rear cover
6) Disassemble HDD

- Remove 1 pcs screw for fixing HDD
- Hold unit with right hand, remove HDD with left hand, put HDD to specified place.

7) Disassemble CPU & I/O Shielding

- Remove 7 screws for fixing CPU shielding & I/O
- Remove CPU shielding.
- Remove DDR cover.
- Remove I/O shielding.

8) Disassemble speaker

- Remove 4 pcs screws for fixing speaker.
- Unplug speaker cable.
- Take R/L speaker out.

9) Disassemble stand support
13) Disassemble WLAN

1. Remove tape.
2. Pull antenna cable out.
3. Remove 2pcs screws.
4. Pull WLAN card out.

14) Disassemble INVERTER

1. Route inverter cable out of hook.
2. Route inverter cable & camera cable out of hook.
3. Unplug inverter cable & camera cable from MB side.
4. Unplug inverter cable.
5. Remove 2pcs screws for fixing inverter.
6. Take inverter out.

15) Disassemble MB
16) Remove power switch card

17) Disassemble webcam & antenna cable

18) Separate BASE pan& bezel
Remove 6 screws.

Separate base pan & front bezel.

Remove 4 screws for locking base pan & LCD. Separate LCD & base pan.